IFIC status and plans

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Budget 2023

- ► My own project (2021-2024)
 - Should cover the glue R&D part (purchases of glue for tests, tool manufacturing and/or acquisition, dummy sensors for tests...)
 - Sr90 radiactive source recently acquired
- ▶ In October: recently approved budget for 2023-2024 (with possible extenstion in 2025, to be clarified)
 - 1 postdoc (start in March)
 - 1 student (start in March?)
 - Equipment → lab equipment such dry cabinet, gluing robot and accessories, etc.

Companies already contacted, waiting for the first round of glue R&D for decission.

- ~20-25K for expendables (including sensors)
- Money still not in our pockets !!
- More news: the IFIC has a cold plasma device for cleaning sensors before gluing → get ride out of oxydation layers!
 - Example https://www.youtube.com/watch?v=DN5rCKOS52k



Conductive glue options

- ▶ IFIC is having discussions within CALICE and FCAL experts
- ▶ After my visit to Tel Aviv (Nov 2022), few alternatives under consideration:
 - "Standard" Epoxy-silver (or even Epoxy-gold!)
 - Anysothropic Film Bonding.
 - Micropearls (still an unknwown for me) → Sekisui company https://www.sekisui.de/products%20and%20technologies/fine-chemicals/micropearls
- ▶ Is the silver part of the glue creating a problem due to neutron radiation??
 - Still unclear. Discussions with Sasha and others on this.
 - Nuclear scientists from IFIC have some experience with neutron lines: nTOF at CERN and HISPANOS in Sevilla. First discussions started, shall we schedule a meeting with more experts in January?



| Epoxy based options

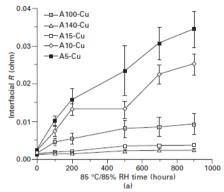
- ► EJ2189 (silver based)
 - Standard of CALICE.
 - Allows low temperature curing (40 or even 23 degrees)
 - Life pot of only few hours.
- ► H20E (silver based)
 - The standard comercial choice. Passes the NASA outgassing standards.
 - Curing at (at least) 80degrees for 3h.
 - Life pot of 3 days!!
- ► H44 (GOLD Based)
 - More expensive. Waiting for a note on this → update: the 0.5oz price is 6kE !!!. (to be compared with 400euros for loz of the others)
 - 1 component only: 6 month pot life. (longer lead times)
 - Passes the NASA outgassing standards.
 - Requires 150degrees curing
 - Gold may offer less oxydation (gold vs aluminium) and less activation due to neutrons.

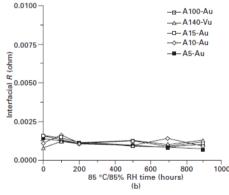




Tests to be done January-April 2023

- ▶ We have purchased a set of dummy substrates with aluminum and gold bath (as the Hammatsu sensors)
 - Delivery in ~ January
- We have orderd the epoxys (still waiting for the note on the gold based).
 - Delivery in January-February
- ▶ Yan is designing a special kapton fanout to be glued to the dummy sensors and perform resitance measurements of the glue dots.
 - Using a precision ohmemetre to measure mOhms.
 - Production/delivery?March?
- ▶ We are getting trained in the use of a climatic chamber here at IFIC: the idea is to tests the different glues and surfaces after several humidity cycles and check the resistivity.
- Also access to a x-ray machine for a "visual" inspection.





4.9 Ag ICA contact resistance changes at 85/85: (a) on Cu contacts, (b) on Au contacts, with (c) corresponding bulk resistivity variations.

Bibliography reference on epoxy+silver glues performance (attached to the agenda)







ACF bonding

- ▶ Based on thin film which is conductive only in Z-axis (anysothopic conductivity)
- ▶ Requires a thermal bonding (up to 150degrees, but very localised and only for few seconds).
 - Issue for CALICE PCBs... what about the FCAL fanouts?
- Example:
 - https://www.youtube.com/watch?v=biHFJFHpqdM
- ▶ In our case, every wafer will have 16 bonding stripes of ~4mm, each one for a row.
- ► Contacted 2 companies:
 - AMADA weld offers a test trial in Holland.
 - If satisfied, we could have two options: 1) they do the bonding for us or 2) we purchase a bonding machine suitable for us. This latter option seems complicated although I have no ballpark for the price (but a "simple" gluing robot costs ~20KE)
 - More discussions with experts needed.

